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# **PRODUCT CHANGE NOTICE**

**Alternate Manufacturing Site  
for Assembly of the Listed  
Intersil QFN Packaged  
Products**

**Refer to:  
PCN11136**

**Date: August 13, 2012**

August 13, 2012

To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Site for Assembly of the Listed Intersil QFN Products –  
STATS ChipPAC (SCM) - Kuala Lumpur, Malaysia**

*PCN11136 has been updated to inform customers that Intersil has withdrawn the notice that was issued on December 22, 2011. The use of the STATS ChipPAC (SCM) facility as an alternate site for assembly of the listed products as outlined in the notice has been canceled. The contents of the original notice are included below.*

This notice is to inform you that Intersil is using the STATS ChipPAC (SCM) facility, located in Kuala Lumpur, Malaysia, as an alternate site for performing assembly of the listed QFN (Quad Flat No Lead) packaged products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The product and site-specific qualification activities are complete.

Products affected:

ISL6267HRZ	ISL95831AHRTZ-T	ISL95831HRTZ-T
ISL6267HRZ-T	ISL95831AHRTZR5493A	ISL95831HRTZ-TS2568
ISL88731CHRTZ	ISL95831AHRTZTR5493A	ISL95831HRTZ-TS2705
ISL88731CHRTZ-T	ISL95831BHRTZ-T	ISL95831IRTZ
ISL95831AHRTZ	ISL95831HRTZ	ISL95831IRTZ-T

The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and currently qualified as a primary supplier to Intersil for assembly of QFN packaged products. There will be no change in the mold compound, bond wire material/diameter, package outline drawing (POD), or moisture sensitivity level (MSL). The qualified material set combinations for assembly and other key items are as follows:

Key Items	Current	New (SCM)
Mold Compound	Sumitomo EME-G770 series	
Die Attach	Hysol QMI 519	Ablebond 8290
Bond Wire	1.0 mil Copper Palladium (CuPd)	
Moisture Sensitivity Level	3	
Device Marking - Site Code	W	M

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at SCM may also be identified by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at SCM is "M".

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Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

*Jon Brewster*

Jon Brewster  
Intersil Corporation

PCN11136

CC: J. Touvell D. Decrosta D. Foster B. Lee S. Nadarajah J. Wei

CANCELLED

## PCN11136 – Reliability Summary

<b>Device: ISL88731C ( 28L 5x5 TQFN )</b>					
<b>Stress / Conditions</b>	<b>Duration</b>	<b>Test lots</b>			<b>Result</b>
		<b>Lot #1</b>	<b>Lot #2</b>	<b>Lot #3</b>	
MSL classification	L3 PBFfree	0/60	NA	NA	PASS
uHAST 130C / 85% RH	96 Hrs	0/77	0/77	0/77	PASS
Temp Cycle -65C to +150C	500 cycles	0/77	0/77	0/77	PASS
Wire pull after 500 TC	NA	0/2	0/2	0/2	PASS

<b>Device: ISL6267C ( 48L 6x6 QFN )</b>					
<b>Stress / Conditions</b>	<b>Duration</b>	<b>Test lots</b>			<b>Result</b>
		<b>Lot #1</b>	<b>Lot #2</b>	<b>Lot #3</b>	
MSL classification	L3 PBFfree	0/77	0/77	0/77	PASS
uHAST 130C / 85% RH	96 Hrs	0/77	0/77	0/77	PASS
Temp Cycle -65C to +150C	500 cycles	0/77	0/77	0/77	PASS
Wire pull after 500 TC	NA	0/2	0/2	0/2	PASS